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Attorney's Docket No.: 06618-720001 / CIT-3325

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Eui-Hyeok Yang et al Art Unit : 2812
Serial No. : 10/005,765 Examiner : Unknown
Filed : November 2, 2001
Title : WAFER-LEVEL TRANSFER OF MEMBRANES IN SEMICONDUCTOR
PROCESSING

Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Applicants call attention to the attached Information Disclosure Statement and documents listed on form PTO-1449.

This filing is being made before the receipt of a first Office action on the merits. No fee is required.

The documents are in the English language; hence no concise explanation is necessary per Rule 98(a)(3).

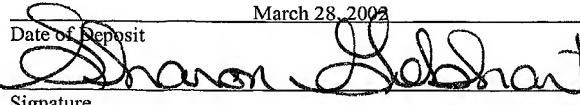
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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

March 28, 2002

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Sharon Gebhart

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Consideration of the foregoing and enclosures plus the return of a copy of the enclosed form PTO-1449 with the Examiner's initials in the left column per MPEP 609 are earnestly solicited along with an early action on the merits.

Respectfully submitted,


BING AI
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Date: March 28, 2002

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Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 06618-720001	Application No. 10/005,765
Information Disclosure Statement by Applicant (Use several sheets if necessary)		APR 08 2002 FCCS-7 (37 CFR §1.98(b))	
		Applicant Eui-Hyeok Yang and Dean V. Wiberg	Filing Date November 2, 2001
		Group Art Unit 2812	

U.S. Patent Documents

Examiner Initial	Desig. ID	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						

Foreign Patent Documents or Published Foreign Patent Applications

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
	AJ						
	AK						
	AL						

Other Documents (include Author, Title, Date, and Place of Publication)

Examiner Initial	Desig. ID	Document
	AM	K.F. Harsh, W. Zhang, V.M. Bright and Y.C. Lee, "Flip-Chip Assembly for Si-Based RF MEMS", Proc. MEMS '99, Orlando, Florida, pp. 273-278, Jan 1999
	AN	T. Akiyama, U. Stufer and N de Rooij, "Wafer-and Piece-Wise Si Tip Transfer Technologies for Applications in Scanning Probe Microscopy", IEEE Journal of Microelectromechanical Systems, pp. 65-70, 1999
	AO	A. Singh, D.A. Horsley, M. Cohn, A. Pisano and R.T. Howe, "Batch Transfer of Microstructures using Flip-Chip Solder Bonding", IEEE Journal of Microelectromechanical Systems, pp. 27-33 1999.
	AP	H. Nguyen, P. Patterson, H. Toshiyoshi and M.C. Wu, "A Substrate-Independent Wafer Transfer Technique for Surface-Micromachined Devices", Proc MEMS Conference, 2000

Examiner Signature	Date Considered
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	